

RESIN COMPACT, METHOD FOR PRODUCING RESIN COMPACT, RESIN
COMPOSITION, METHOD FOR PRODUCING RESIN COMPOSITION AND
ELECTRONIC COMPONENT DEVICE

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ABSTRACT

10 The present invention is related to a method for
producing a resin compact containing an epoxy resin, a curing
agent, a curing accelerator and an inorganic filler. The
method includes a kneading and crushing process for preparing
a first powder material obtained by mixing, heat-melting,
15 kneading and crushing a first component containing the epoxy
resin and the curing agent and the inorganic filler, but not
containing the curing accelerator; a pulverizing process for
preparing a second powder material obtained by pulverizing a
second component containing the curing accelerator; a mixing
20 process for preparing a resin composition by dispersing and
mixing the first powder material and the second powder
material; and a molding process for obtaining the resin
compact by compression-molding the resin composition. This
makes it possible to obtain a resin compact (particularly, a
25 resin compact for encapsulation) having superior long term
storage stability at room temperature, good curable property
and fluidity.

Fig. 1 accompanies the abstract

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